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Electronic Patent Application Submission
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EFS ID: 24718
Application ID: 09687048
Title of Invention: LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH
First Named Inventor: Kuri-shi Lee
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Submission Type: Information
Disclosure Statement

Application Number: 09/687,048
Attorney Docket Number: AMKOR-052A

LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

First Named Inventor: Kuri-shi Tae Heon Lee

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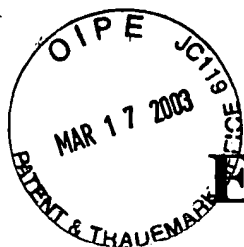
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Electronic Information Disclosure Statement

LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

Application:



09/687048

Confirmation: 1120

Applicant(s): Kuri-shi Lee

Docket

Number:

AMKOR-052A

Group Art

Unit:

2814

Examiner:

Dilinh P. Nguyen

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US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents